L ANALOG MULTIPLEXER/DEMULTIPLEXER TH INJECTION-CURRENT EFFECT CONTROL SCLS542B – SEPTEMBER 2003 – REVISED JANUARY 2004
D, DGV, N, OR PW PACKAGE (TOP VIEW)
Y6 [2 15] Y2 COM [3 14] Y1
Y7 🛛 4 13 🗍 Y0
Y5 []5 12 [] Y3 INH []6 11 [] A
NC 7 10 B GND 8 9 C NC – No internal connection

description/ordering information

This eight-channel CMOS analog multiplexer/demultiplexer is pin compatible with the '4051 function and, additionally, features injection-current effect control, which has excellent value in automotive applications where voltages in excess of normal supply voltages are common.

The injection-current effect control allows signals at disabled analog input channels to exceed the supply voltage without affecting the signal of the enabled analog channel. This eliminates the need for external diode/resistor networks typically used to keep the analog channel signals within the supply-voltage range.

TA	PDIP – N Tube SQIC – D		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74HC4851N	HC4851N
		Tube	SN74HC4851D	110 1051
-40°C to 125°C	SOIC – D	Tape and reel	SN74HC4851DR	HC4851
-40 C 10 125 C		Tube	SN74HC4851PW	110 4054
	TSSOP – PW	Tape and reel	SN74HC4851PWR	HC4851
	TVSOP – DGV Tape and r		SN74HC4851DGVR	HC4851

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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	FU	NCTION	TABLE	
	INP	UTS		ON
INH	С	В	Α	CHANNEL
L	L	L	L	Y0
L	L	L	Н	Y1
L	L	Н	L	Y2
L	L	Н	Н	Y3
L	Н	L	L	Y4
L	Н	L	Н	Y5
L	Н	Н	L	Y6
L	Н	Н	Н	Y7
Н	Х	Х	Х	None

logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} Input voltage range, V_I (see Note 1) Switch I/O voltage range, V_{IO} (see Notes 1 and Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) . I/O diode current, I_{IOK} ($V_{IO} < 0$ or $V_{IO} > V_{CC}$)	d 2)	$\begin{array}{c} \dots \dots -0.5 \ \mbox{V to } \ \mbox{V}_{CC} + 0.5 \ \mbox{V} \\ \dots \dots -0.5 \ \mbox{V to } \ \mbox{V}_{CC} + 0.5 \ \mbox{V} \\ \dots \dots \dots \pm 20 \ \mbox{mA} \end{array}$
Switch through current, $I_T (V_{IO} = 0 \text{ to } V_{CC})$		±25 mA
Continuous current through V _{CC} or GND		±50 mA
Package thermal impedance, θ_{JA} (see Note 3)	: D package	73°C/W
-	DGV package	120°C/W
	N package	67°C/W
	PW package	108°C/W
Storage temperature range, T _{stg}		

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 5.5 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
VCC	Supply voltage		2	6	V
		$V_{CC} = 2 V$	1.5		
		V _{CC} = 3 V	2.1		
VIН	High-level input voltage, control inputs	V _{CC} = 3.3 V	2.3		V
		V _{CC} = 4.5 V	3.15		
		V _{CC} = 6 V	4.2		
		V _{CC} = 2 V		0.5	
		V _{CC} = 3 V		0.9	
VIL	Low-level input voltage, control inputs	V _{CC} = 3.3 V		1	V
		$V_{CC} = 4.5 V$		1.35	
		V _{CC} = 6 V		1.8	
VI	Control input voltage		0	VCC	V
VIO	Input/output voltage		0	VCC	V
		$V_{CC} = 2 V$		1000	
		V _{CC} = 3 V		800	
Δt/Δv	Input transition rise or fall time	V _{CC} = 3.3 V		700	ns
		V _{CC} = 4.5 V		500	
		V _{CC} = 6 V		400	
TA	Operating free-air temperature	·	-40	125	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				Τį	λ = 25°C	;	UP TO	85°C	UP TO	125°C	
	PARAMETER	TEST CONDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2.V		500	650		670		700	
	_	$I_T \le 2 \text{ mA},$	3 V		215	280		320		360	
ron	On-state switch resistance	$V_I = V_{CC}$ to GND, $V_{INH} = V_{IL}$	3.3 V		210	270		305		345	Ω
	Switch resistance	(see Figure 5)	4.5 V		160	210		240		270	
			6 V		150	195		220		250	
			2.V		4	10		15		20	
	Difference in	l⊤ ≤ 2 mA,	3 V		2	8		12		16	
Δr_{on}	on-state resistance	$V_{I} = V_{CC}/2,$	3.3 V		2	8		12		16	Ω
	between switches	$V_{INH} = V_{IL}$	4.5 V		2	8		12		16	
			6 V		3	9		13		18	
lj –	Control input current	$V_I = V_{CC} \text{ or } GND$	6 V			±0.1		±0.1		±1	μA
	Off-state switch leakage current (any one channel)	VI = V _{CC} or GND, VINH = VIH (see Figure 6)				±0.1		±0.5		±1	
IS(off)	Off-state switch leakage current (common channel)	VI = V _{CC} or GND, VINH = VIH (see Figure 7)	6 V			±0.2		±2		±4	μA
I _{S(on)}	On-state switch leakage current	VI = V _{CC} or GND, VINH = VIL (see Figure 8)	6 V			±0.1		±0.5		±1	μΑ
ICC	Supply current	$V_I = V_{CC}$ or GND	6 V			2		20		40	μA
CIC	Control input capacitance	A, B, C, INH			3.5	10		10		10	pF
C _{IS}	Common terminal capacitance	Switch off			22	40		40		40	pF
COS	Switch terminal capacitance	Switch off			6.7	15		15		15	pF

injection current coupling specifications, T_A = –40°C to 125°C

	PARAMETER	VCC	TEST CO	NDITIONS	MIN	TYP†	MAX	UNIT
		3.3 V				0.05	1	
		5 V		l ‡ ≤ 1 mA		0.1	1	
	Maximum shift of output voltage of enabled analog	3.3 V	R _S ≤ 3.9 kΩ	1 + 1 1 0 1		0.345	5	
V∆ _{out}		Maximum shift of output voltage of enabled analog	5 V		l _l ‡ ≤ 10 mA		0.067	5
V∆out	channel	3.3 V		. +		0.05	2	mV
		5 V		l ‡ ≤ 1 mA		0.11	2	
		3.3 V	R _S ≤ 20 kΩ	1,1 < 10 = 1		0.05	20	
		5 V		lj‡ ≤ 10 mA		0.024	20	

[†] Typical values are measured at $T_A = 25^{\circ}C$. [‡] I_I = total current injected into all disabled channels



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switching characteristics over recommended operating free-air temperature range, $V_{CC} = 2 V$, $C_L = 50 pF$ (unless otherwise noted) (see Figures 9–14)

		FROM	то	Тд		;	UP TO	85°C	UP TO	125°C	
F	PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
^t PLH ^t PHL	Propagation delay time	COM or Yn	Yn or COM		19.5	25		29		32	ns
^t PLH ^t PHL	Propagation delay time	Channel Select	COM or Yn		23	30		35		40	ns
^t PZH ^t PZL	Enable delay time	INH	COM or Yn			95		105		115	ns
^t PHZ ^t PLZ	Disable delay time	INH	COM or Yn			95		105		115	ns

switching characteristics over recommended operating free-air temperature range, $V_{CC} = 3 V$, $C_L = 50 pF$ (unless otherwise noted) (see Figures 9–14)

		FROM	то	Τį	λ = 25°C	;	UP TO	85°C	UP TO	125°C	
F	PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
^t PLH ^t PHL	Propagation delay time	COM or Yn	Yn or COM		12	15.5		17.5		19.5	ns
^t PLH ^t PHL	Propagation delay time	Channel Select	COM or Yn		13.5	17.5		20		23	ns
^t PZH ^t PZL	Enable delay time	INH	COM or Yn			90		100		110	ns
^t PHZ ^t PLZ	Disable delay time	INH	COM or Yn			90		100		110	ns

switching characteristics over recommended operating free-air temperature range, $V_{CC} = 3.3 \text{ V}$, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figures 9–14)

		FROM	то	Т	ן = 25°C	;	UP TO	85°C	UP TO	125°C	
Р	PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
^t PLH ^t PHL	Propagation delay time	COM or Yn	Yn or COM		11	14.5		16.5		18.5	ns
^t PLH ^t PHL	Propagation delay time	Channel Select	COM or Yn		12.5	16.5		19		22	ns
^t PZH ^t PZL	Enable delay time	INH	COM or Yn			85		95		105	ns
^t PHZ ^t PLZ	Disable delay time	INH	COM or Yn			85		95		105	ns



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switching characteristics over recommended operating free-air temperature range, $V_{CC} = 4.5$ V, $C_{L} = 50$ pF (unless otherwise noted) (see Figures 9–14)

_		FROM	то	Τį	λ = 25°C	;	UP TO 85°C		UP TO 125°C		
F	PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
^t PLH ^t PHL	Propagation delay time	COM or Yn	Yn or COM		8.6	11.5		12.5		13.5	ns
^t PLH ^t PHL	Propagation delay time	Channel Select	COM or Yn		10	13		15		17	ns
^t PZH ^t PZL	Enable delay time	INH	COM or Yn			80		90		100	ns
^t PHZ ^t PLZ	Disable delay time	INH	COM or Yn			80		90		100	ns

switching characteristics over recommended operating free-air temperature range, $V_{CC} = 6 V$, $C_L = 50 pF$ (unless otherwise noted) (see Figures 9–14)

		FROM	то	T _A = 25°C UP TO 85°		85°C	UP TO	125°C			
	PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
^t PLH ^t PHL	Propagation delay time	COM or Yn	Yn or COM		8	10		11		12	ns
^t PLH ^t PHL	Propagation delay time	Channel Select	COM or Yn		9.5	12.5		14.5		16.5	ns
^t PZH ^t PZL	Enable delay time	INH	COM or Yn			78		80		80	ns
^t PHZ ^t PLZ	Disable delay time	INH	COM or Yn			78		80		80	ns

operating characteristics, $T_A = 25^{\circ}C$ (see Figure 15)

	PARAMETER	V _{CC}	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	3.3 V	Nolood	32	"Г
		5 V	No load	37	р⊦



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APPLICATION INFORMATION







Figure 2. Alternate Solution Requires 32 Passive Components and One Extra 6-V Regulator to Suppress Injection Current Into a Standard 'HC4051 Multiplexer



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APPLICATION INFORMATION





Figure 4. Diagram of Bipolar Coupling Mechanism (Appears if V_{IN} Exceeds V_{CC} , Driving Injection Current Into the Substrate)



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PARAMETER MEASUREMENT INFORMATION











Figure 7. Maximum Off-Channel Leakage Current, Common Channel, Test Setup

Figure 8. Maximum On-Channel Leakage Current, **Channel To Channel, Test Setup**



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PARAMETER MEASUREMENT INFORMATION





Analog In to Analog Out



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PARAMETER MEASUREMENT INFORMATION



Figure 15. Power-Dissipation Capacitance Test Setup





10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	•		Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74HC4851D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC4851	Samples
SN74HC4851DGVR	ACTIVE	TVSOP	DGV	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC4851	Samples
SN74HC4851DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-40 to 125	HC4851	Samples
SN74HC4851DRE4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC4851	Samples
SN74HC4851DRG4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC4851	Samples
SN74HC4851N	ACTIVE	PDIP	Ν	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 125	SN74HC4851N	Samples
SN74HC4851PW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC4851	Samples
SN74HC4851PWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-40 to 125	HC4851	Samples
SN74HC4851PWRG4	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC4851	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



PACKAGE OPTION ADDENDUM

10-Dec-2020

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN74HC4851 :

• Automotive: SN74HC4851-Q1

NOTE: Qualified Version Definitions:

• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC4851DGVR	TVSOP	DGV	16	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74HC4851DR	SOIC	D	16	2500	330.0	16.8	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC4851DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC4851DRG4	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC4851PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC4851PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC4851PWRG4	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TEXAS INSTRUMENTS

www.ti.com

PACKAGE MATERIALS INFORMATION

6-Nov-2020



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC4851DGVR	TVSOP	DGV	16	2000	853.0	449.0	35.0
SN74HC4851DR	SOIC	D	16	2500	364.0	364.0	27.0
SN74HC4851DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74HC4851DRG4	SOIC	D	16	2500	333.2	345.9	28.6
SN74HC4851PWR	TSSOP	PW	16	2000	364.0	364.0	27.0
SN74HC4851PWR	TSSOP	PW	16	2000	853.0	449.0	35.0
SN74HC4851PWRG4	TSSOP	PW	16	2000	853.0	449.0	35.0

MECHANICAL DATA

PLASTIC SMALL-OUTLINE

MPDS006C - FEBRUARY 1996 - REVISED AUGUST 2000

DGV (R-PDSO-G**)

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins MO-153

14/16/20/56 Pins – MO-194



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



4211283-4/E 08/12

D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW0016A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



PW0016A

EXAMPLE BOARD LAYOUT

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



PW0016A

EXAMPLE STENCIL DESIGN

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

9. Board assembly site may have different recommendations for stencil design.



^{8.} Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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